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ICEPST 2017
Oct 19-20, 2017
London, United Kingdom

The International Research Conference is a federated organization dedicated to bringing together a significant number of diverse scholarly events for presentation within the conference program. Events will run over a span of time during the conference depending on the number and length of the presentations.

ICEPST 2017 : 19th International Conference on Electronic Packaging, Systems, and Technology is the premier interdisciplinary forum for the presentation of new advances and research results in the fields of Electronic Packaging, Systems, and Technology. The conference will bring together leading academic scientists, researchers and scholars in the domain of interest from around the world. Topics of interest for submission include, but are not limited to:

Advanced and emerging
Advanced and parallel CAD
Advanced Manufacturing
Advanced Packaging and
Components, Packaging and
Electrical performance of
Electromagnetic (EM) and
Electronic packages and
Electronic Packaging,
Emerging and advanced
Emerging Technologies
High-speed channels,
Inter-connection
Jitter and noise
Low power mobile and
Macromodeling and model
Measurement and data
Memory and DDR

Microwave and Power
Microwave Theory and
Multiconductor
Nano interconnects and
New design techniques and
New methodologies and
Novel CAD concepts,
Package-chip co-design
Packaging Design and
Packaging Materials and
Power integrity and power
Quality and Reliability
RF/microwave packaging
Signal and thermal
Solid State Lighting
System-level, board-level
3D interconnects, 3D